

Ratings and Characteristics Curves

($T_A = 25^\circ\text{C}$ unless otherwise noted)

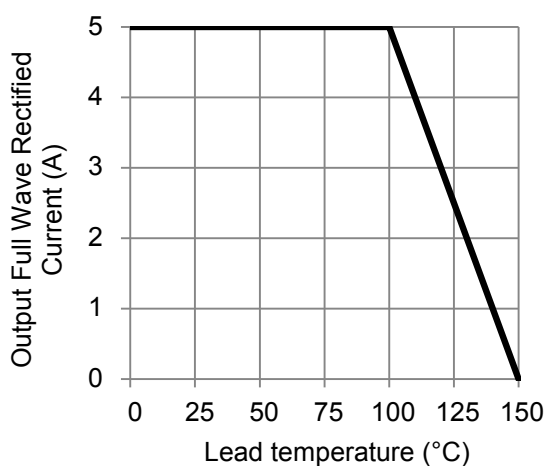


Figure 1. Forward Current Derating Curve

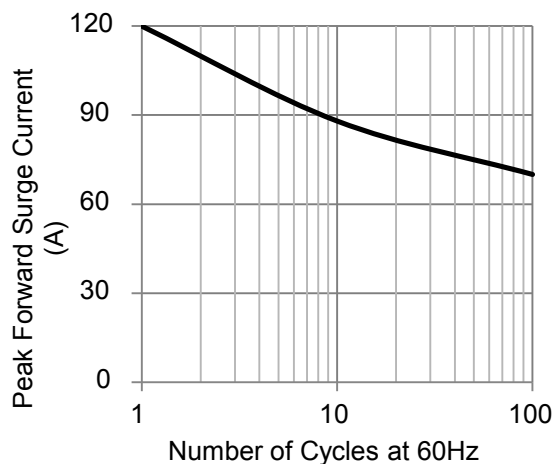


Figure 2. Maximum Non-Repetitive Peak Forward Surge Current

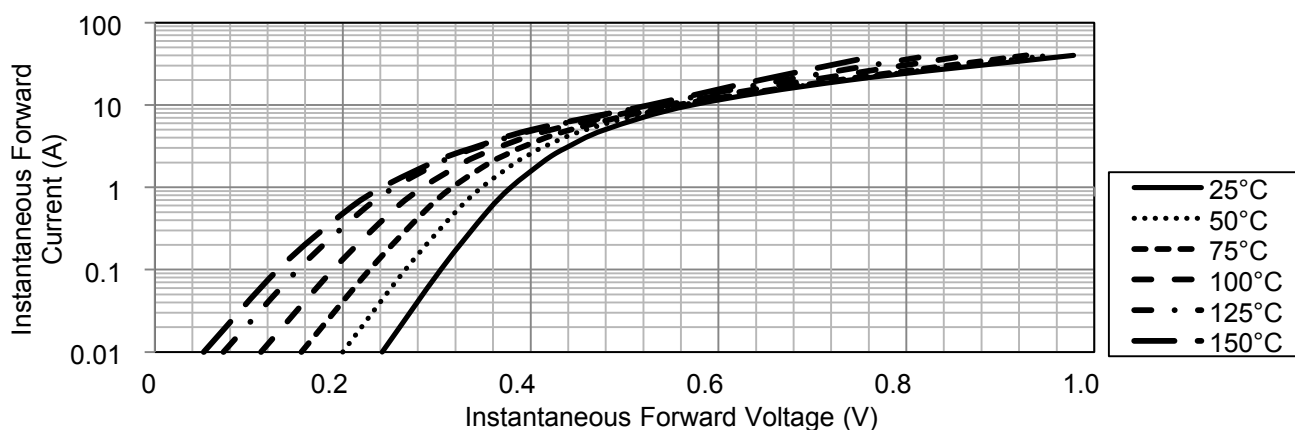


Figure 3. Typical Instantaneous Forward Characteristics
(SK52 thru SK54)

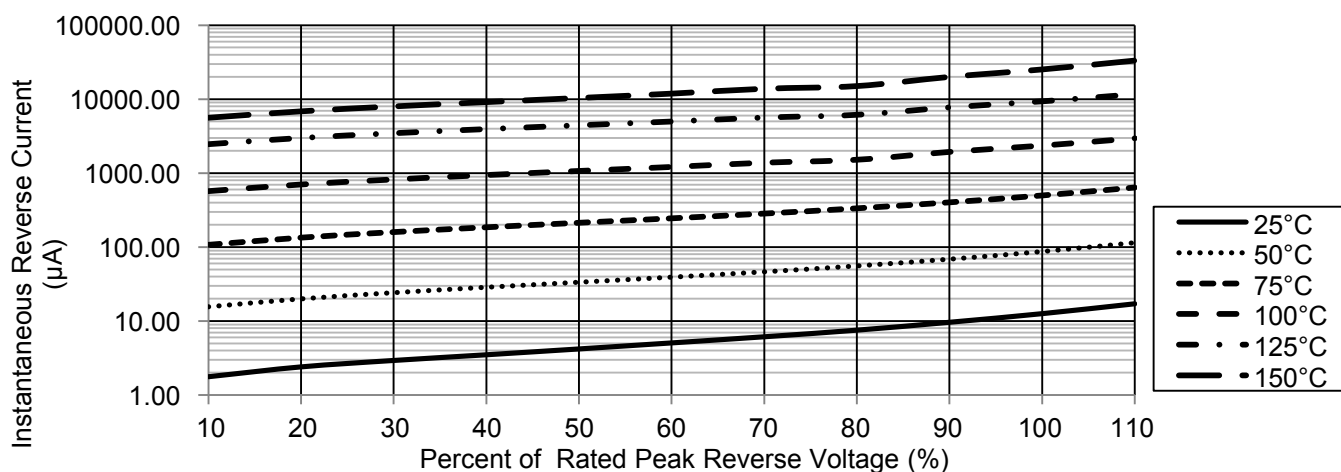


Figure 4. Typical Reverse Characteristics
(SK52 thru SK54)

SK52 thru SK56

Surface Mount Schottky Rectifier
 Reverse Voltage 20-60V Forward Current 5A

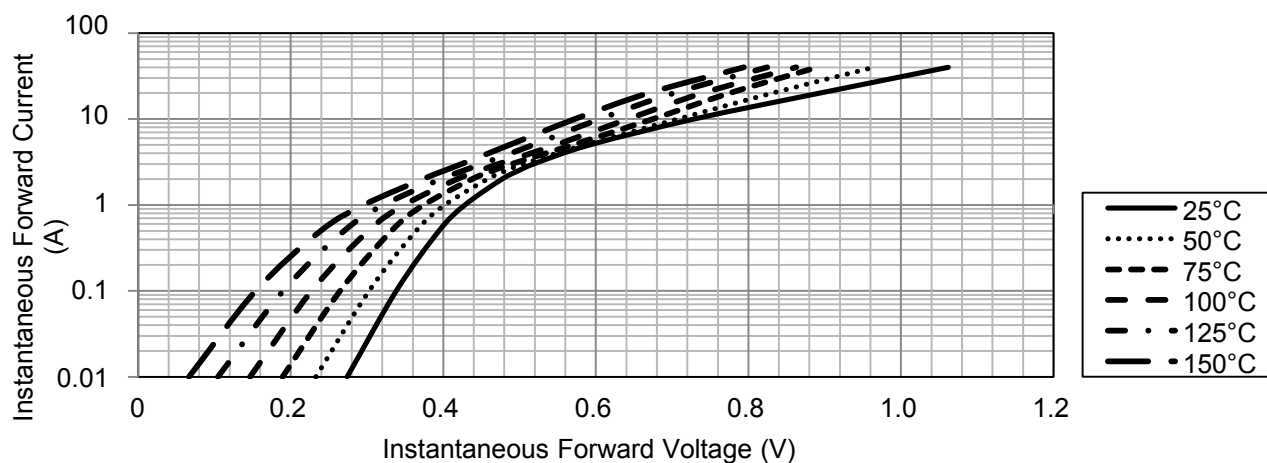


Figure 5. Typical Instantaneous Forward Characteristics
 (SK55 thru SK56)

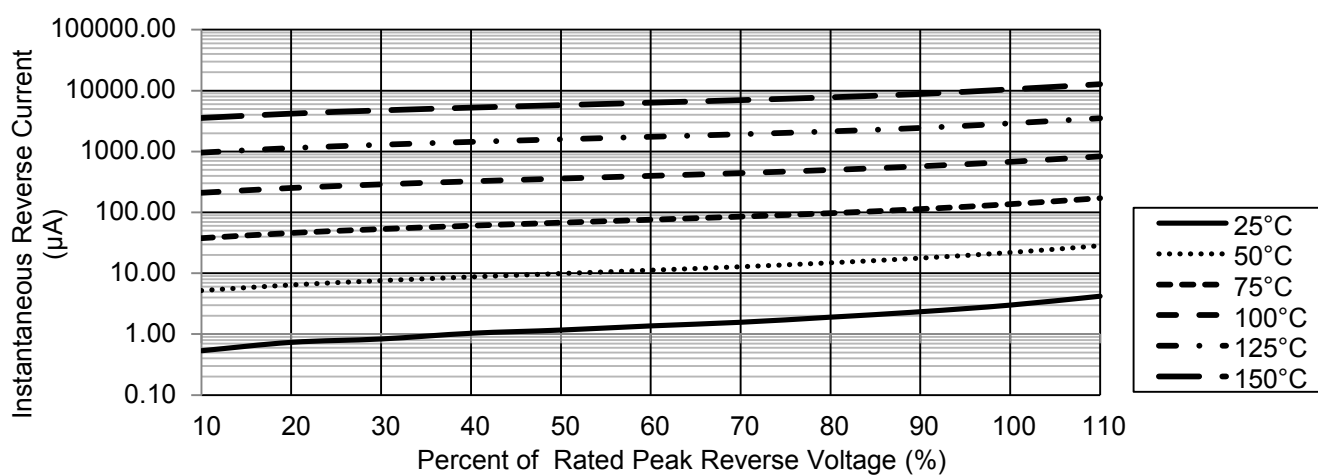
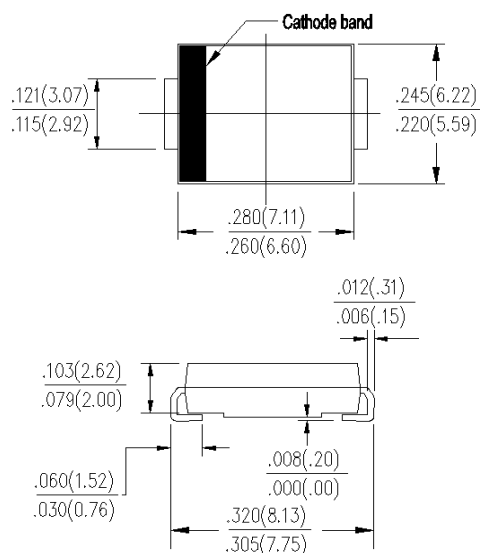


Figure 6. Typical Reverse Characteristics
 (SK55 thru SK56)

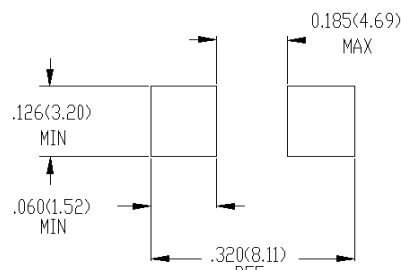
Package Outline Dimensions

in inches (millimeters)

DO-214AB (SMC)



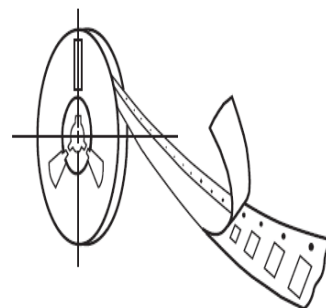
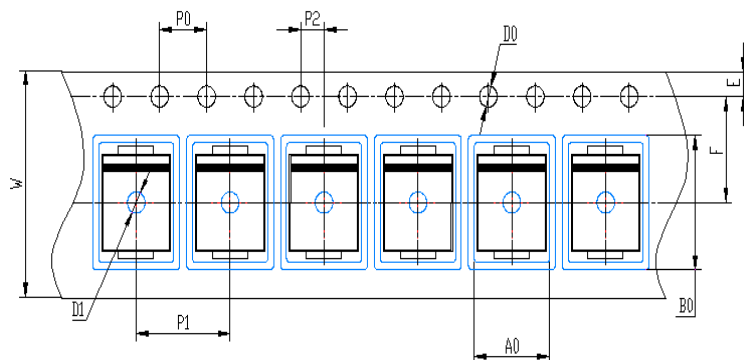
Mounting Pad Layout



Packing Information

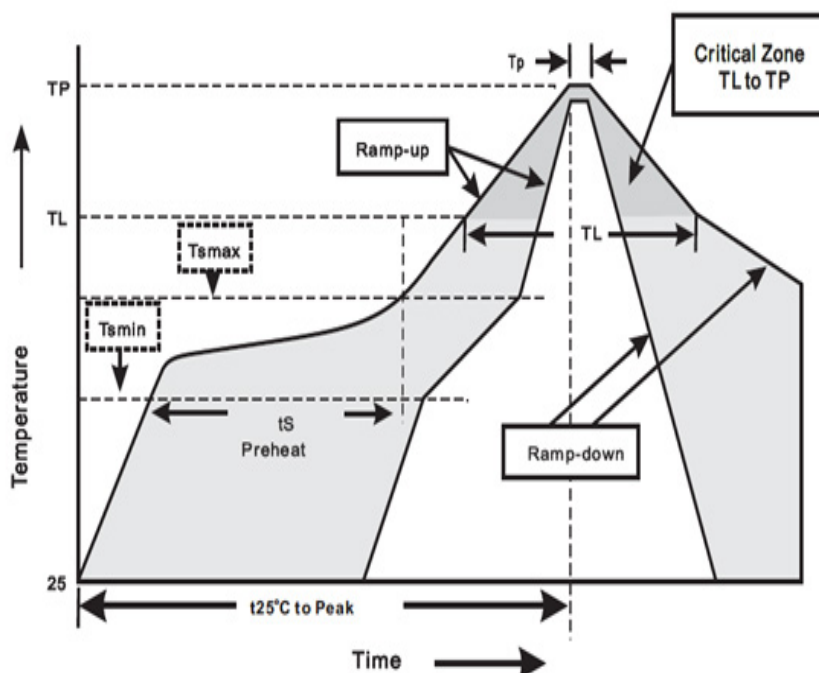
3000 pcs/Reel, 14 Reels/Box; 16mm Tape, 13" Reel

Tape & Reel Specification



Symbol	SMC(mm)
W	16±0.2
E	1.75±0.1
F	7.5±0.05
D0	1.5±0.1
D1	1.50 +0.1/-0
P0	4.0±0.1
P1	8.0±0.1
P2	2.0±0.05
A0	6.22±0.1
B0	8.31±0.1

Soldering Parameters



Reflow Soldering		Sn-Pb Eutectic Assembly	Pb-Free Assembly
Pre Heat	- Temperature Min (Ts min)	100°C	150°C
	- Temperature Max (Ts max)	150°C	200°C
	- Time (min to max) (ts)	60 – 120 secs	60 – 180 secs
Average ramp up rate (Liquidus) Temp (TL) to peak		3°C/second max	3°C/second max
TS(max) to TL - Ramp-up Rate		3°C/second max	3°C/second max
Reflow	- Temperature (TL) (Liquidus)	183°C	217°C
	- Time (min to max) (ts)	60 – 150 seconds	60 – 150 seconds
Peak Temperature (TP)		240+0/-5 °C	240+0/-5°C
Time within 5°C of actual peak Temperature (tp)		10 – 30 seconds	20 – 40 seconds
Ramp-down Rate		6°C/second max	6°C/second max
Time 25°C to peak Temperature (TP)		6 minutes max	8 minutes max
Do not exceed		260°C	260°C

Wave Soldering	
Peak Temperature	260+0/-5°C
Dipping Time	10 seconds
Soldering	1 time